PCN Number:		20160526001						P	PCN Date:		5/26/2016	
Title: Qualification			of new Assembly site (UTAC) for the TLV1702AIRUGR									
Custom	er Cont	act:	PCN	Man	nager [Dept:	Quality Se	rvice	es			
Proposed 1 st Ship Da		te: 8/26/2016		/26/2016	Estin	Estimated Sample Avail			Provided upon Request			
Change	Type:											
Asse	embly Si	te		Assembly Process			\boxtimes	Assembly Materials				
Desi	ign				Electrical Sp	ecifica	tion		Mecha	hanical Specification		
Test	Site				Packing/Shi	pping/l	abeling		Test P	Process		
	er Bump				Wafer Bump					r Bump Process		
Waf	er Fab S	ite			Wafer Fab N		-	Ш	Wafer	er Fab Process		
					Part number change							
					P	CN D	etails					
Descript	tion of (Chang	e:									
the TLV1702AIRUGR d		JGR de	vice	e. C	Construction	differences are noted			UTAC		sembly site for	
	L	Mold C	om	poui	nd	SID	#450176		SID#CZ0290)	
Reason	for Cha	nge:										
Continuit	y of Sup	ply										
Anticipa	ted imp	oact o	n Fit	t, F	orm, Functi	on, Qu	ality or Rel	iabi	lity (p	ositive	e / no	egative):
None												
Anticipa	ted imp	oact o	n Ma	ateı	rial Declara	tion						
No Impact to the Material Declaration				Material Declarations or Product Conter production data and will be available for release. Upon production release the release from the TI ECO website.				ole follo the rev	llowing the production			
Changes	s to pro	duct i	den	tific	cation resul	ting fr	om this PC	N:				
-		sembly Site Origin (22L						e (21L)			nbly City	
Hana Thailand			HNT			THA				Bangkok		
UTAC		NSE			THA					Bar	ngkok	
Texas Instruments MADE IN: Malaysia 20: 20: 20: 20: 20: 20: 20: 20: 20: 20:												
Assembly site code for HNT= H Assembly site code for NSE = J												

Product Affected

TLV1702AIRUGR



TI Information Selective Disclosure

Qualification Report

TLV1702AIRUG in UTAC

Approve Date 20-Apr-2016

Product Attributes

Attributes	Qual Device: TLV1702AIRUG	QBS Package Reference: TLV342IRUGR
Assembly Site	UTAC	UTAC
Package Family	X2QFN	X2QFN
Flammability Rating	UL 94 V-0	UL 94 V0
Wafer Fab Supplier	FFAB	DFAB
Wafer Process	BICOM3XHV	50A21

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: TLV1702AIRUG	QBS Package Reference: TLV342IRUGR
AC	Autoclave 121C	96 Hours	-	3/231/0
ED	Electrical Characterization	Per Datasheet Parameters	Pass	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/225/0
HBM	ESD - HBM	2000 V	-	-
CDM	ESD - CDM	1500 V	-	-
HTOL	Life Test, 125C	1000 Hours	-	-
HTOL	Life Test, 150C	300 Hours	-	3/231/0
HTSL	High Temp. StorageBake, 150C	1000 Hours	-	3/231/0
HTSL	High Temp. StorageBake, 170C	420 Hours	2/154/0	-
LU	Latch-up	(per JESD78)	-	-
PD	Physical Dimensions		-	3/15/0
SD	Solderability	Pb Free, 8 Hours Steam Age	3/30/0	3/66/0
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0	3/231/0
UHAST	Unbiased HAST, 130C/85%RH	96 Hours	3/231/0	-
WBP	Wire Pull	Wires	-	3/228/0
WBS	Ball Bond Shear	Wires	-	3/228/0

Green/Pb-free Status:

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com

⁻ QBS: Qual By Similarity - Qual Device TLV1702AIRUG is qualified at LEVEL1-260CG

⁻ Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/